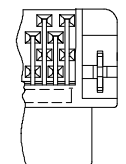
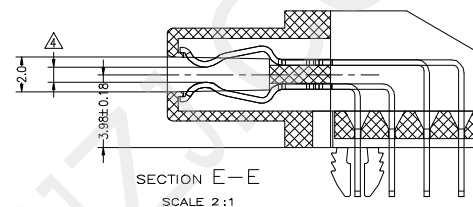


FOR 20,40,60,80,100,120 POSITIONS ONLY



FOR 30,50 POSITIONS ONLY



SPECIFICATIONS

Rated Current:1.0AMP

Contact Resistance:35mΩ Max

Withstand Voltage:500V AC/DC

Insulation Resistance:500MΩ Min

Operation Temperature:-40°C to +105°C

MATERIAL:

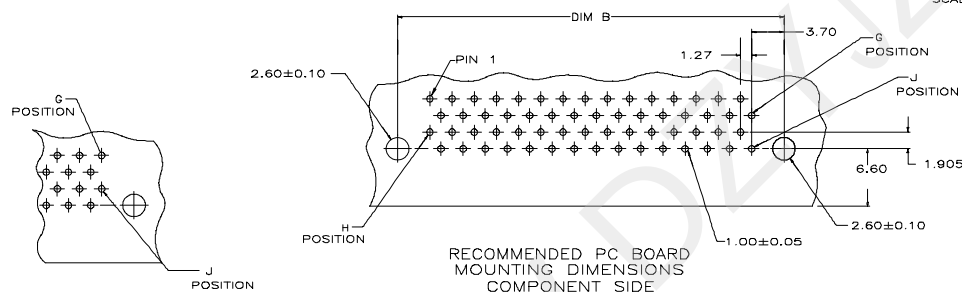
Contact Material:Phosphor bronze

Boardlocks:Brass

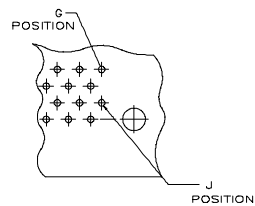
Insulator Material:LCP Polyester(UL94V-0)

Max.Processing Temp: 230°C for 30-60 seconds
(260°C for 10 seconds)

2. FINISH:

CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA,
3.81μm MIN. MATTE-TIN ON SOLDER TAIL, OVER
1.27mm MIN. NICKEL UNDERPLATED.BOARDLOCKS: 3.81μm MIN. TIN-Cu OVER
1.27mm MIN. UNDERPLATED.3. G, J, AND H INDICATES NUMBER OF POSITION MARKED ON ASSEMBLY.
ALSO SEE TABLE.4. CONNECTOR SOLDER TAILS WILL ACCOMMODATE PRINTED CIRCUIT BOARD
THICKNESS OF 0.80 TO 1.60RECOMMENDED PC BOARD
MOUNTING DIMENSIONS
COMPONENT SIDE

FOR 20,40,60,80,100,120 POSITIONS ONLY

FOR 30,50
POSITIONS ONLY

深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SCSI 母座全塑 90° DIP
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC60-SCSIXX-254
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-2209131720
			SHEET NO. 1 OF 1